

You are cordially invited to attend the following talks involving Nova technology and customer collaboration:

SPIE. ADVANCED LITHOGRAPHY

CONFERENCE 10585

Metrology, Inspection, and Process Control for Microlithography XXXII

FEBRUARY
26
MONDAY

Scatterometry for gate all around (GAA) technology enablement [10585-4]
Speaker: Roy Koret, Nova Measuring Instruments Ltd. (Israel)
2:10 PM SESSION 2 (Optical Metrology)

FEBRUARY
27
TUESDAY

Scatterometry and x-ray metrology for in-line control of spin-transfer torque magnetic random access memory (STT-MRAM) devices [10585-118]
Speaker: Davide Crotti, IMEC (Belgium)
11:10 AM SESSION 5 (Challenges and New Methods)

FEBRUARY
28
WEDNESDAY

Implementation of machine learning for high volume manufacturing metrology challenges [10585-32]
Speaker: Padraig R. Timoney, GLOBALFOUNDRIES (USA)
8:20 AM SESSION 8 (Hybrid Metrology & Machine Learning)

FEBRUARY
28
WEDNESDAY

Novel hybrid metrology for process integration of gate all around (GAA) devices [10585-34]
Speaker: Raja Muthinti, IBM Research, Albany NanoTech, NY (USA)
9:00 AM SESSION 8 (Hybrid Metrology & Machine Learning)

FEBRUARY
28
WEDNESDAY

In-line characterization of non-selective SiGe nodule defects with scatterometry enabled by machine learning [10585-35]
Speaker: Dexin Kong, IBM Research, Albany NanoTech, NY (USA)
9:20 AM SESSION 8 (Hybrid Metrology & Machine Learning)

FEBRUARY
28
WEDNESDAY

Lines roughness holistic metrology sensitivity study supported by EUV mask designed with induced roughness [10585-36]
Speaker: Shimon Levi, Applied Materials Ltd. (Israel)
9:40 AM SESSION 8 (Hybrid Metrology & Machine Learning)

FEBRUARY
28
WEDNESDAY

Selectivity process control using in-line XPS for self-assembly monolayer-based selective deposition process [10585-38]
Speaker: Silvia Armini, IMEC (Belgium)
10:50 AM SESSION 9 (New Methods and Machine Learning)

FEBRUARY
28
WEDNESDAY

Context-based virtual metrology [10585-39]
Speaker: Peter Ebersbach, GLOBALFOUNDRIES (Germany)
11:10 AM SESSION 9 (New Methods and Machine Learning)

CONFERENCE 10585

Advanced Etch Technology for Nanopatterning VII

FEBRUARY
27
TUESDAY

Exploration of post-lithography smoothing methods applied to 16nm half-pitch EUV lines and spaces[10589-9]
Speaker: Frederic Lazzarino, IMEC (Belgium)
10:30 AM SESSION 4 (Innovations in Plasma and Patterning Materials)

SHORT COURSE

FEBRUARY
25
SUNDAY

Scatterometry in Profile, Overlay and Focus Process Control [SC1100]
Instructors: Hugo Cramer, ASML Netherlands B.V. (Netherlands); Igor Turovets, Nova Measuring Instruments Ltd. (Israel)
1:30 PM - 5:30 PM